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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF:

Yukihiro YANAGAWA, et al.

GROUP: 1775

SERIAL NO: 10/542,053

FILED: July 12, 2005

EXAMINER: LAVILLA, MICHAEL E

FOR: RESIN FORMING MOLD AND PRODUCTION METHOD FOR THE RESIN
FORMING MOLD

SUBMISSION OF SUPPLEMENTAL APPLICATION DATA SHEET

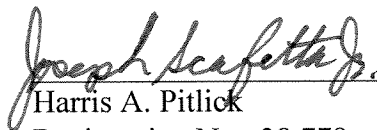
Office of Initial Patent Examination
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Applicant(s) submit herewith a Supplemental Application Data Sheet for the above-identified application for the purpose of correcting the inventors' cities of residence.

Respectfully Submitted,

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